

ABSTRACT

A substrate processing method includes stacking a first die and a second die on a target substrate in this order. The target substrate includes an insulating film and a plurality of electrodes on a surface of the target substrate facing the first die. The first die includes an insulating film and one or more electrodes on a surface of the first die facing the target substrate, and further includes an insulating film and one or more electrodes on a surface of the first die facing the second die. The second die includes an insulating film and one or more electrodes on a surface of the second die facing the first die. The method further includes bonding the insulating film of the target substrate to the insulating film of the first die; bonding the plurality of electrodes of the target substrate to the one or more electrodes of the first die; bonding the insulating film of the first die to the insulating film of the second die; and bonding the one or more electrodes of the first die to the one or more electrodes of the second die.

Fig. 5